

REMARKS/ARGUMENTS

Favorable reconsideration of the present application is respectfully requested.

Claims 1-4 remain active in the application.

Claims 1-4 were rejected under 35 U.S.C. §102 as being anticipated by the U.S. patent to Fuschetti. The Examiner there indicated that this reference discloses first and second soldering layers at 33 and 33, respectively.

Applicants wish to thank Examiner Parsons for the courtesy of an interview on January 14, 2004, at which time the outstanding rejection was discussed. In particular, Applicants pointed out that claims 1 and 2 recite the first soldering layer as being positioned to connect the heat radiation side insulating substrate and the case, whereas the second soldering layer is used to connect the heat radiation side insulating substrate and the ends of semi-conductor chips, wherein the first and second soldering layers are the same in raw material. In contrast, the two elements 33 in Fuschetti are located between the substrates and the chips, i.e., at the locations of the second soldering layer. There is no description in Fuschetti of the composition of any adhering layer at the claimed location of the first soldering layer, i.e., between the “case” 12 and the “heat absorption side insulating substrate” 20. It was therefore agreed that, pending the Examiner’s further review of this reference, the rejection based upon Fuschetti would be withdrawn.

The specification and claims have been amended to respond to the formal objections noted in paragraphs 1 and 2 of the Office Action.

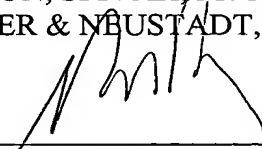
Application No. 10/059,392

Reply to Office Action of November 18, 2003

Applicants therefore believe that the present application is in a condition for allowance and respectfully solicit an early Notice of Allowability.

Respectfully submitted,

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